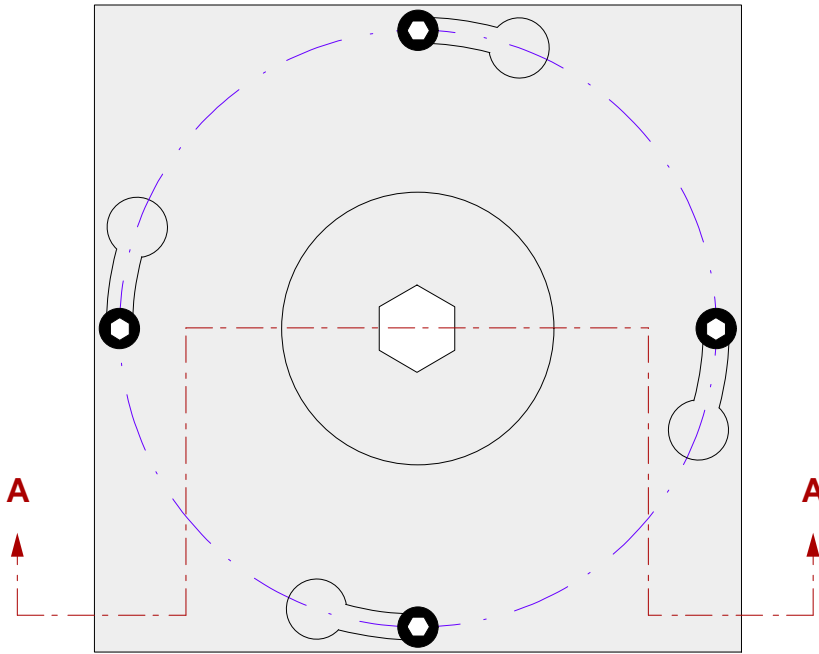


GHz BGA Socket - Direct mount, solderless

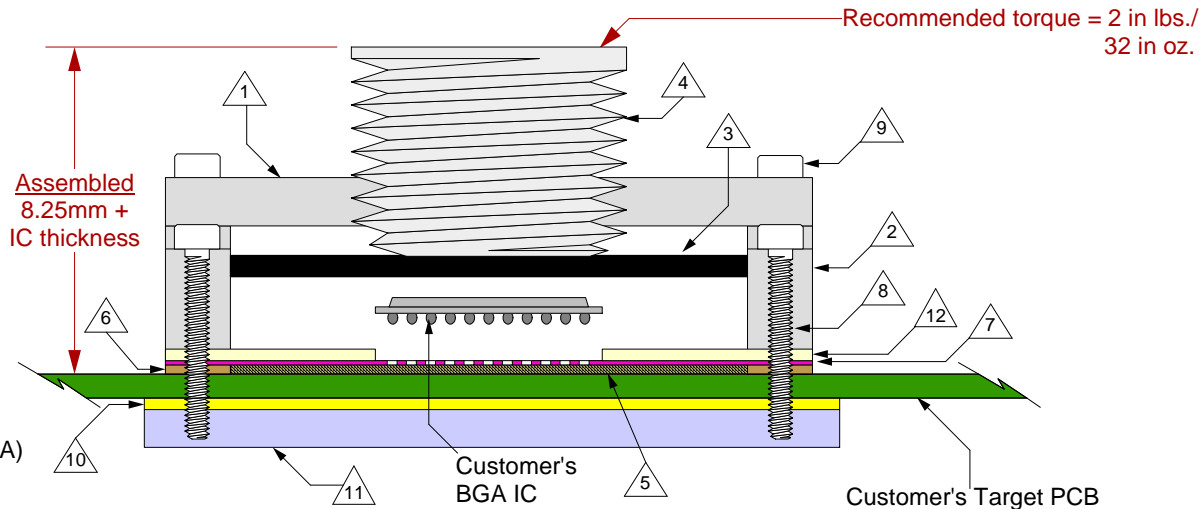
Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Easily removable swivel socket lid

Top View



Side View
(Section AA)



- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- △ 6 Elastomer Guide: Non-clad FR4. Thickness = 0.475mm.
- △ 7 Ball Guide: Kapton polyimide.
- △ 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread , 9.525mm long.
- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 10 Insulation Plate: FR4/G10, Thickness = 1.59mm.
- △ 11 Backing Plate: Black anodized Aluminum. Thickness = 6.35mm.
- △ 12 IC Guide: Torton

SG-BGA-7050 Drawing

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11351 Rupp Drive, Suite 400, Burnsville, MN 55337
Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: D

Drawing: H. Hansen

Date: 6/20/05

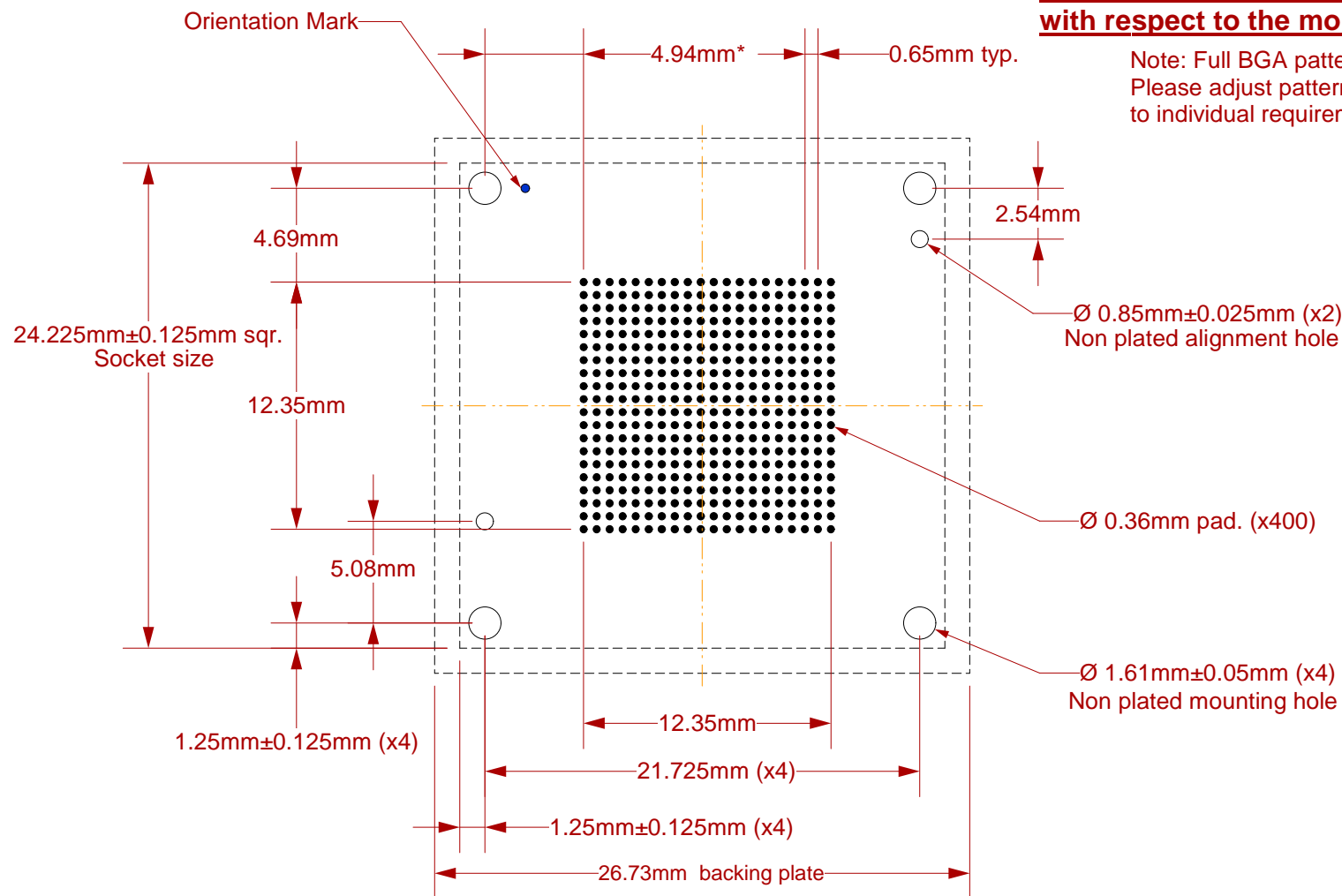
File: SG-BGA-7050 Dwg

Modified: 07/08/15, DH

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**

Note: Full BGA pattern shown.
Please adjust pattern according to individual requirements.




Target PCB Recommendations

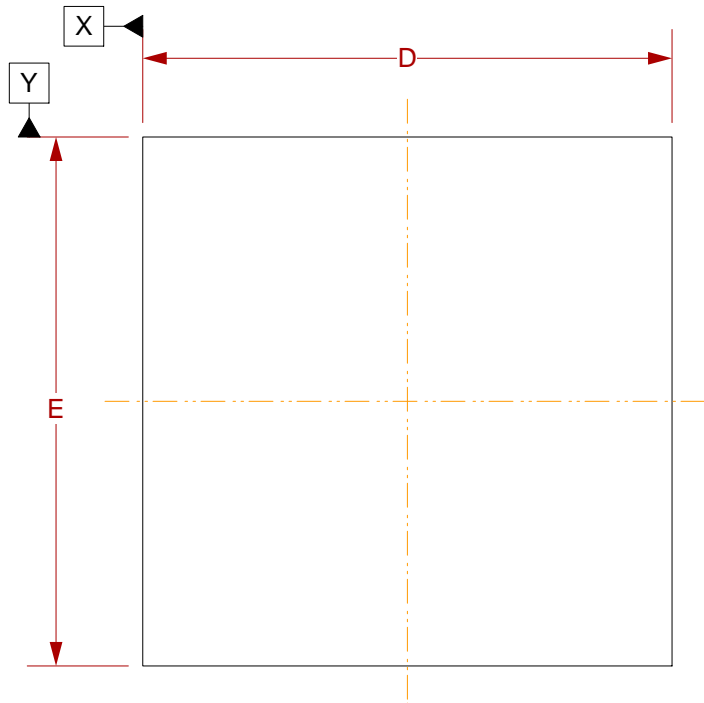
Total thickness: 1.6 mm min.

Plating: Gold or Solder finish

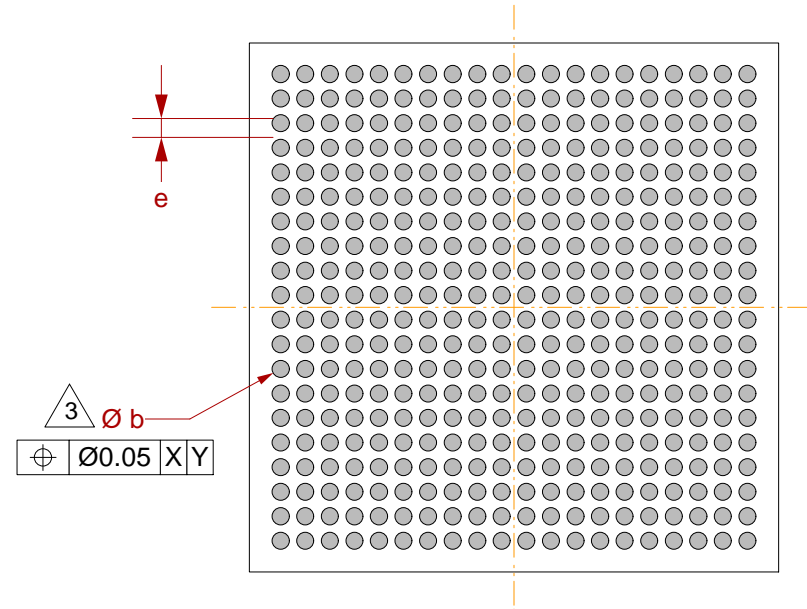
PCB Pad height: Same or higher than solder mask

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

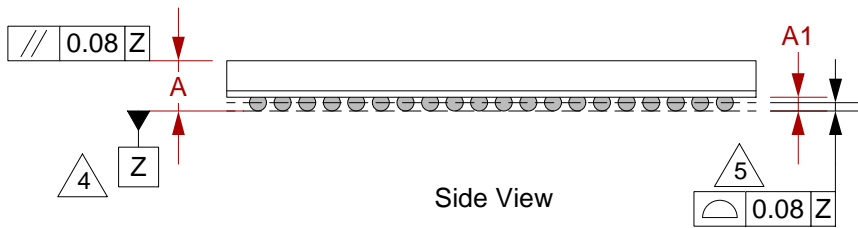
 <p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	SG-BGA-7050 Drawing		Status: Released	Scale: 4:1	Rev: D
	Drawing: H. Hansen		Date: 6/20/05		
	File: SG-BGA-7050 Dwg		Modified: 07/08/15, DH		



Top View



Bottom View



Side View


1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z .
- 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

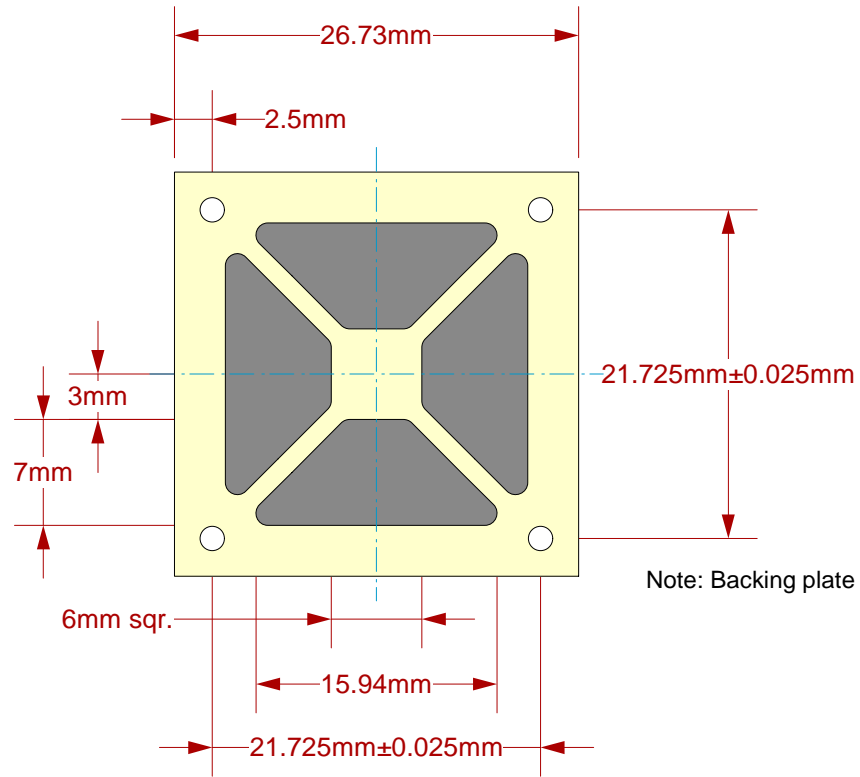
DIM	MIN	MAX
A		1.33
A1	0.27	0.37
b		0.45
D	14.0 BSC	
E	14.0BSC	
e	0.65 BSC	

20 x 20 array

All dimensions are in mm unless stated otherwise

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	Drawing: H. Hansen		Date: 6/20/05		
	File: SG-BGA-7050 Dwg		Modified: 07/08/15, DH		

Top View




Note: Backing plate holes are tapped to accept 0-80 screws.

Front View



Description: Insulation Plate and Backing Plate

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		File: SG-BGA-7050 Dwg	Modified: 07/08/15, DH	

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)